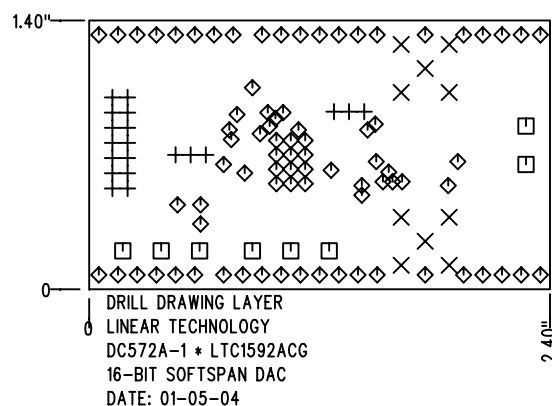


REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		

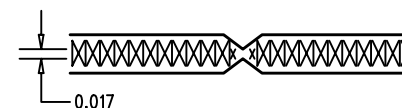


SHOWN FROM COMPONENT SIDE


SIZE	QTY	SYM	PLTD
0.035	20	+	PLTD
0.055	10	X	PLTD
0.064	8	□	PLTD
0.015	81	◇	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. SCORING:



6. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE		
DRAWN			TITLE: FABRICATION DRAWING 16-BIT SOFTSPAN DAC	
CHECK				
DESIGN	KIM T.	01-05-04		
ENGR	MARK T.	01-05-04		
			SIZE A	REV. A
SCALE = NONE			DES- 0000	SHT 1 of 1